



DEFENSE LOGISTICS AGENCY
 LAND AND MARITIME
 POST OFFICE BOX 3990
 COLUMBUS, OH 43218-3990

March 29, 2018

Mr. Scott Bryan
 Sierra Circuits, Inc.
 1108 West Evelyn Ave
 SunnyVale, CA 94086

Dear Mr. Bryan:

RE: Notification of Qualification, MIL-PRF-31032C, FSC 5998; CN060941, CN060942,
 VQ (VQE-18-032408)

Qualification of your products is granted under the current issue of the specification as a result of successful qualification testing to Department of Defense Performance Specification MIL-PRF-31032, Printed Circuit Board/Printed Wiring Board, and associated specifications MIL-PRF-31032/1 and MIL-PRF-31032/2. The capabilities indicated below shall be listed on Qualified Manufacturers List QML-31032. The effective date of this qualification is March 29, 2018.

MANUFACTURER NAME & ADDRESS Sierra Circuits, Inc. 1108 West Evelyn Ave SunnyVale, CA 94086	PLANT LOCATION Same	CAGE Code: 0ZHS4 Phone: 408-735-7137 Fax: Email: ScottB@protoexpress.com
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CAPABILITIES BY TECHNOLOGY / ASSOCIATED SPECIFICATION:

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
 Qualification Letters: VQE-18-032408
 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant
 Max. Panel Size: 18" x 24"
 Max. Number of Layers: 20
 Max. Board Thickness: .100"
 Min. Hole Size: .007" Laser Ablated Plated Hole Size Before Plating, 0.01" Drilled Plated-Through Hole Before Plating
 Aspect Ratio: 0.6:1 Microvia, 10:1 Through-Hole
 Min. Conductor Width/Space: .004"/.004"
 Hole Preparation: Plasma Etchback
 Hole Wall Conductive Coating: Electroless Copper
 Copper Plating: Periodic Reverse Plate
 Hole Fill/Via Plug: Non-Conductive
 Solder Resist: Liquid Photoimageable
 Finish System: HASL, ENIG
 Additional Fab Capabilities: Foil Lamination, Blind Vias,
 Controlled Impedance: Differential, Single-Ended

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
Qualification Letters: VQE-18-032408
Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
Max. Panel Size: 18" x 24"
Max. Number of Layers: 20
Max. Board Thickness: .100"
Min. Hole Size: .007" Laser Ablated Plated Hole Size Before Plating, 0.01" Drilled Plated-Through Hole Before Plating
Aspect Ratio: 0.6:1 Microvia, 10:1 Through-Hole
Min. Conductor Width/Space: .004"/.004"
Hole Preparation: Plasma Etchback
Hole Wall Conductive Coating: Electroless Copper
Copper Plating: Periodic Reverse Plate
Hole Fill/Via Plug: Non-Conductive
Solder Resist: Liquid Photoimageable
Finish System: HASL, ENIG
Additional Fab Capabilities: Foil Lamination, Blind Vias,
Controlled Impedance: Differential, Single-Ended

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Test report number 31032-5027-18 has been assigned to your test data for the GI base material qualification and test report number 31032-5038 for the GF base material qualification. Your first QML status report shall cover the period from **April 1, 2018 through June 30, 2018** and is due to this office by **August 31, 2018**. Your first biennial CVI report for this initial qualification shall cover the period from **April 1, 2018 through December 31, 2019**, and is due to this office by **March 1, 2020**. This qualification is based on your MIL-PRF-31032 certification and are subject to the conditions stated below:

1. A listing on the Qualified Manufacturers List (QML) does not guarantee acceptance of the product(s) in any future purchase.
2. QML listing does not constitute a waiver of any requirements of the specification or of the provisions of any contract.
3. Advertising of qualification information is permitted. Permission to use such information for advertising or publicity purposes is granted provided that such publicity or advertising does not state or imply that the product(s) is the only product of that type qualified or that the Department of Defense in any way recommends or endorses the manufacturer's product.
4. The listing applies only to products produced in the plant(s) specified in this letter of notification of qualification and applies to future amendments or revisions of the specification, unless otherwise notified.
5. The listing applies only to materials and manufacturing construction techniques identical to or covered by that (those) qualified. The qualifying activity must be advised in advance of any change to the materials and manufacturing construction techniques. Failure to notify the qualifying activity of any change to the materials and manufacturing construction techniques is cause for removal from the QML.

Because we are held responsible for the accuracy and currency of this QML, please let us know if your company discontinues production utilizing these materials or processes. If you have any questions, please contact Mr. Samuel Wagers, (614) 692-9567 or vqe.sw@dla.mil.

Sincerely,

for ALAN J. WILL
Chief
Sourcing and Qualifications Division